

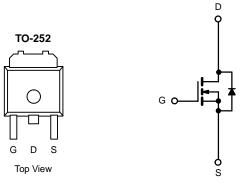
# 6414ANG-VB Datasheet N-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>(BR)DSS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)			
100	0.030 at V <sub>GS</sub> = 10 V	40			
100	0.035 at V <sub>GS</sub> = 4.5 V	37			

## FEATURES

- Trench Power MOSFETS
- 175 °C Junction Temperature
- Low Thermal Resistance Package





N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> $T_{C}$ = 25 °C, unless otherwise noted					
Parameter	-	Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	100	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	- V	
Continuous Drain Current ( $T_1 = 175 \text{ °C}$ )	T <sub>C</sub> = 25 °C	1-	40		
Continuous Drain Current $(1) = 173$ C)	T <sub>C</sub> = 125 °C	I <sub>D</sub>	23	_	
Pulsed Drain Current		I <sub>DM</sub>	120	A	
Avalanche Current		I <sub>AR</sub>	35		
Repetitive Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AR</sub>	61	mJ	
	T <sub>C</sub> = 25 °C	P	107 <sup>b</sup>	14/	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C <sup>c</sup>	– P <sub>D</sub> –	3.75	- W	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	(PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Case (Drain)		R <sub>thJC</sub>	1.4	0/10	

Notes:

a. Duty cycle ≤ 1 %.

b. See SOA curve for voltage derating.

c. When Mounted on 1" square PCB (FR-4 material).

\* Pb containing terminations are not RoHS compliant, exemptions may apply.

SPECIFICATIONS $T_{\rm J}$ = 25 $^\circ$	C, unless o	therwise noted					
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{SS} = 0 V, I_D = 250 \mu A$	100		V		
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1		3	v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		V <sub>DS</sub> = 100 W <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μA	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250	1	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	75			А	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5 A		0.030		1	
	-	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 3 \text{ A}$		0.035		-	
Drain-Source On-State Resistance <sup>a</sup>	r <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5 A, T <sub>J</sub> = 125 °C		0.053		Ω	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A, T <sub>J</sub> = 175 °C		0.067			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A	10			S	
Dynamic <sup>b</sup>	4		<u>.</u>	+	<u> </u>		
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		2600		pF	
Output Capacitance	C <sub>oss</sub>			290			
Reverse Transfer Capacitance	C <sub>rss</sub>			120			
Total Gate Charge <sup>c</sup>	Qg			35	60	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 50 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 40 \text{ A}$		11			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			9			
Gate Resistance	R <sub>G</sub>			1.7		Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			11	20		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 50 V, $R_L$ = 1.25 $\Omega$		12	20	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$\text{I}_\text{D} \cong$ 40 A, $\text{V}_\text{GEN}$ = 10 V, $\text{R}_\text{G}$ = 2.5 $\Omega$		30	45		
Fall Time <sup>c</sup>	t <sub>f</sub>			12	20		
Source-Drain Diode Ratings and Cha	aracteristics 7	Γ <sub>C</sub> = 25 °C <sup>b</sup>					
Continuous Current	۱ <sub>S</sub>				40		
Pulsed Current	I <sub>SM</sub>			1	120	A	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 30 A, V <sub>GS</sub> = 0 V		1.0	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			60	100	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 30 A, di/dt = 100 A/μs		5	8	Α	
Reverse Recovery Charge	Q <sub>rr</sub>			0.15	0.4	μC	

Notes:

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

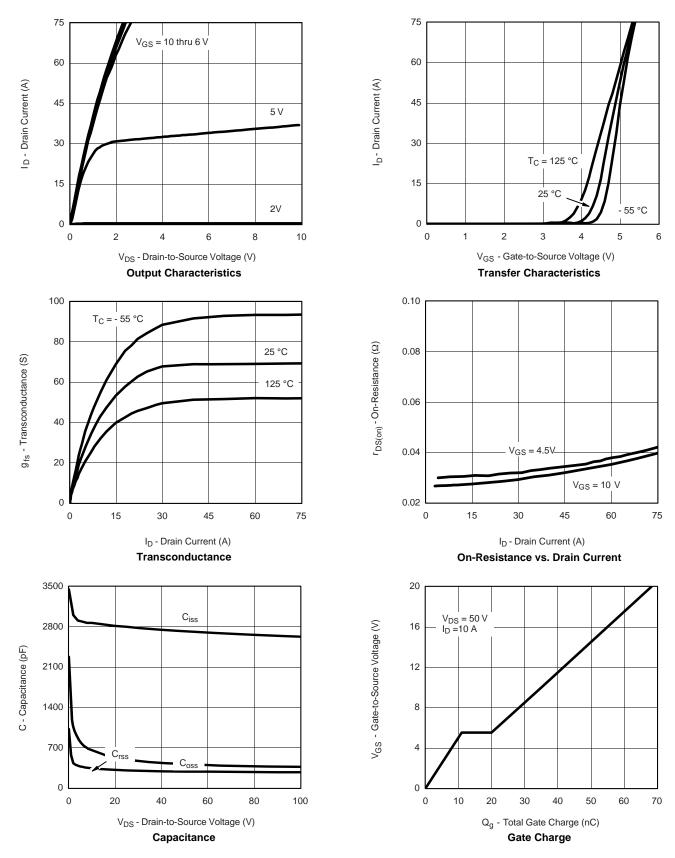
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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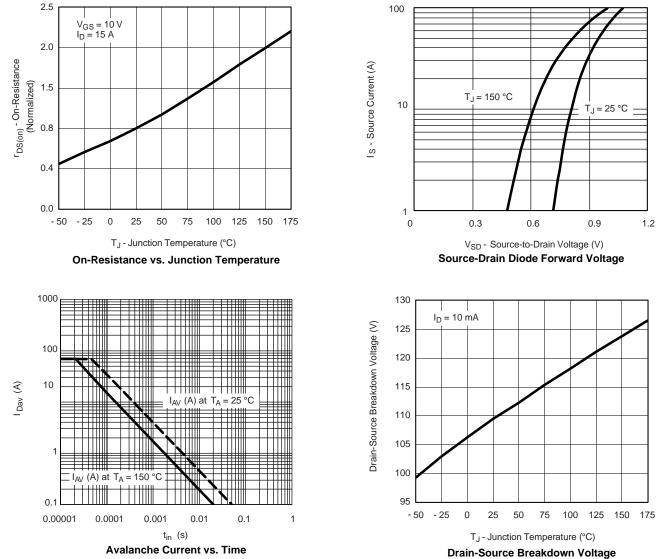




服务热线:400-655-8788



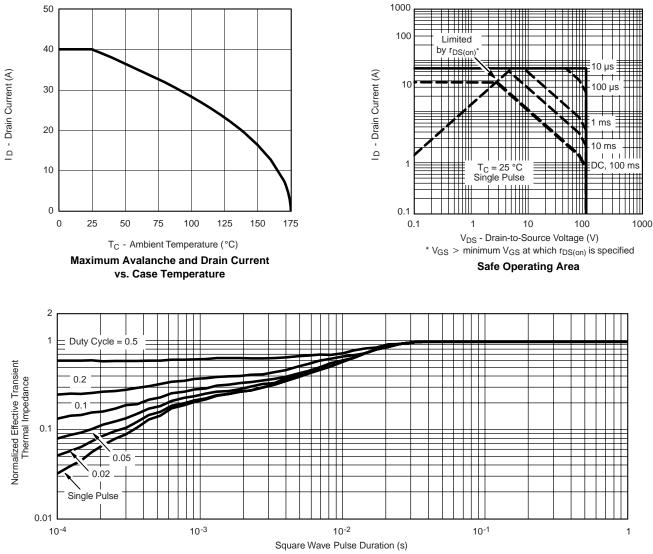
### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



vs. Junction Temperature



#### THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



# **TO-252AA CASE OUTLINE**





	MILLIN	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	2.28 BSC		0.090 BSC	
e1	4.56 BSC		0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347					

#### Note

• Dimension L3 is for reference only.



### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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